FY2026/3 (29th Term)

Financial Results

Supplementary Material

2026/5/12

V Technology Co., Ltd.

Tokyo Stock Exchange Prime Market / Code: 7717

Index

Financial Results Overview

FY2026/3 Results

Business overview

✓ **Semiconductor & Photomask segment net sales rose 32% YoY, achieving a record high**
✓ **Improved profitability in the FPD contributed to higher profits; operating profit doubled YoY**
✓ **Fell short of announced plan due to partial postponement of photomask and CF exposure equipment and recording of product warranty-related costs**
✓ **Semiconductor & Photomask segment order intake was ¥23.4 bn, up ¥6.8 bn YoY**

Order intake: **¥56.3 bn**
YoY +¥3.6 bn

Net sales: **¥53.0 bn**
YoY +¥6.8 bn

Operating profit: **¥3.8 bn**
YoY +¥1.9 bn

Net Profit (attributable to owners of parent) : **¥2.3 bn**
YoY +¥1.5 bn

ROE **6.6%**
FY2025/3 2.4%

FY2027/3 Forecast

Business overview

✓ **Semiconductor & Photomask segment net sales expected to grow 60% YoY, a substantial expansion**
✓ **Semiconductor & Photomask segment profitability expected to exceed FPD**
✓ **Given uncertainty in the Middle East, certain risks are factored into expenses**
✓ **Orders centered on advanced packaging expected to continue growing**

Order intake:
YoY Expected to increase

Net sales: **¥60.0 bn**
YoY +¥7.0 bn

Operating profit: **¥5.5 bn**
YoY +¥1.7 bn

Net Profit Profit (attributable to owners of parent) : **¥3.0 bn**
YoY +¥0.7 bn

ROE **8.0%**
FY2026/3 6.6%

FY2026/3
Consolidated Financial Results

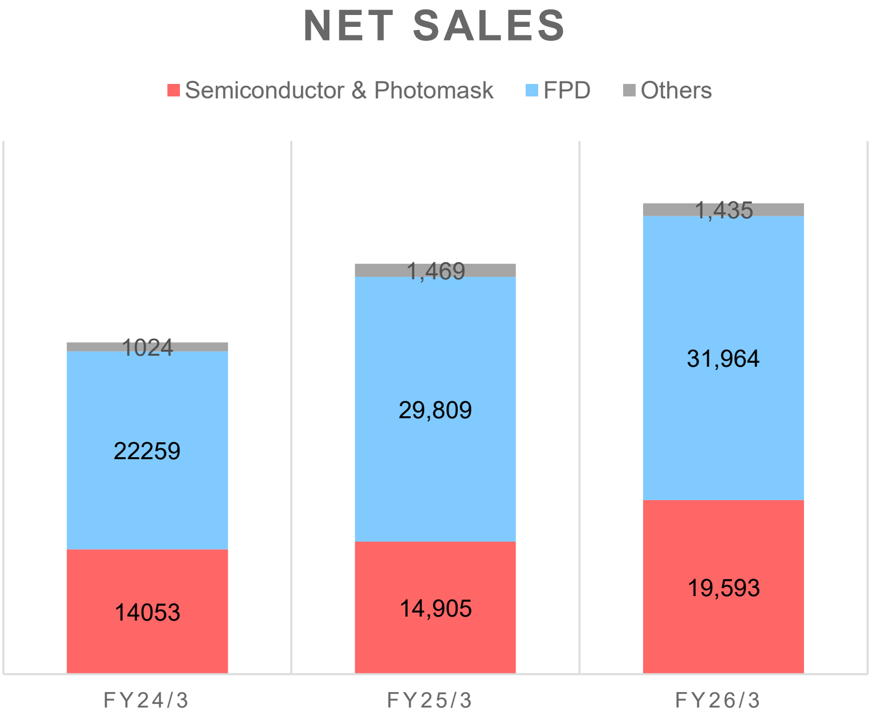
Net Sales and Order Intake Trends by Segment

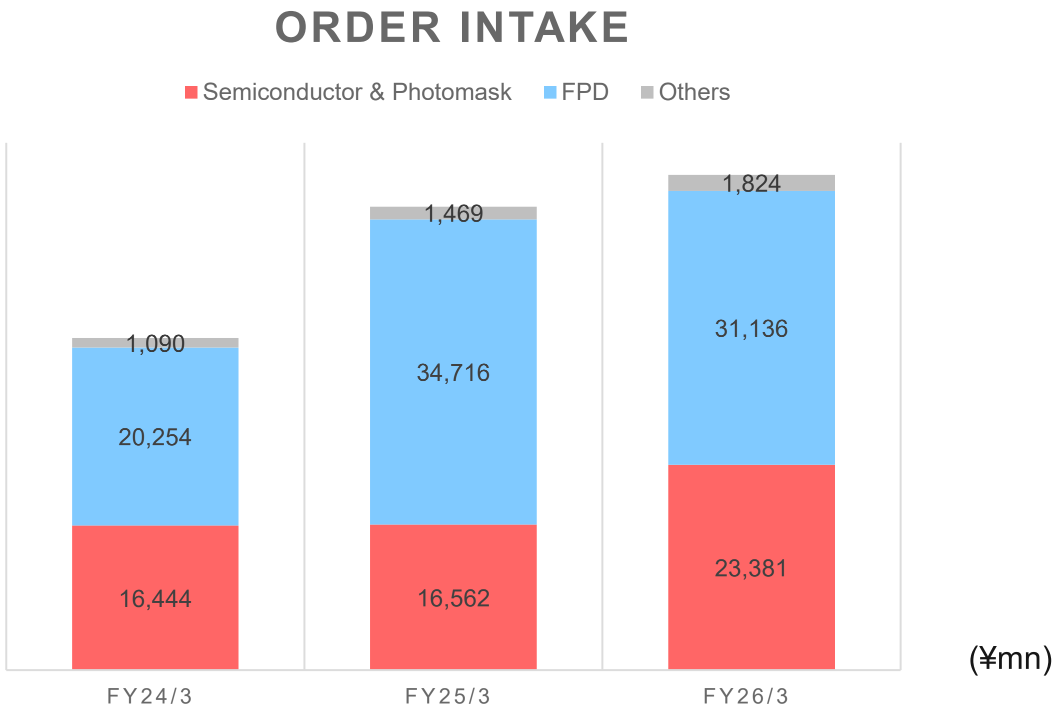
Semiconductor & Photomask

- ✓ **FY2026/3 order intake driven by advanced packaging and semiconductor wafer inspection equipment**
- ✓ **On the sales side, while these performed strongly, photomasks declined significantly**

FPD

- ✓ **FY2026/3 order intake: Maintenance increased, while CF exposure equipment and others declined**
- ✓ **Inspection equipment remained flat in both net sales and order intake**





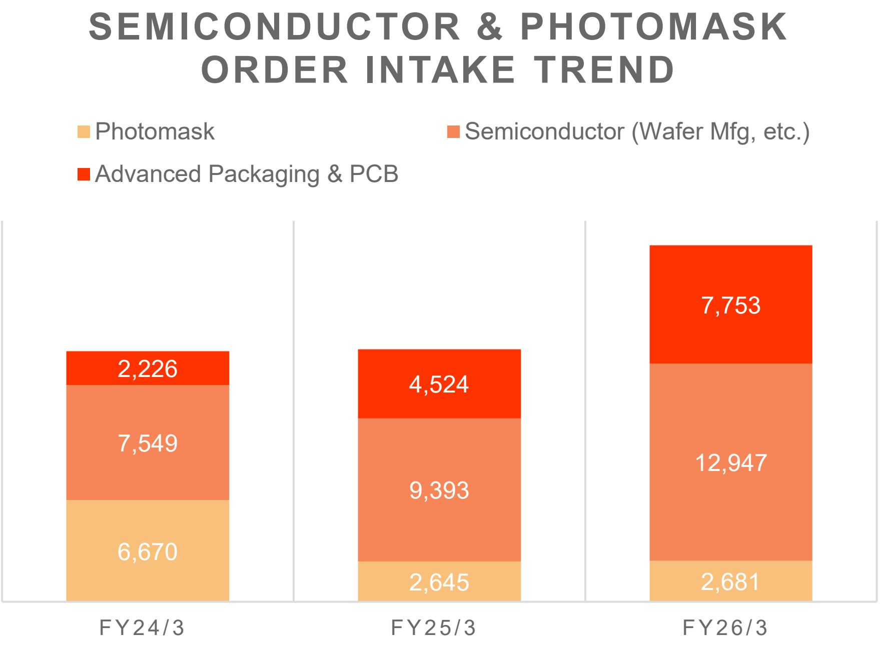
Sub-segment Order Intake Trends

Semiconductor & Photomask

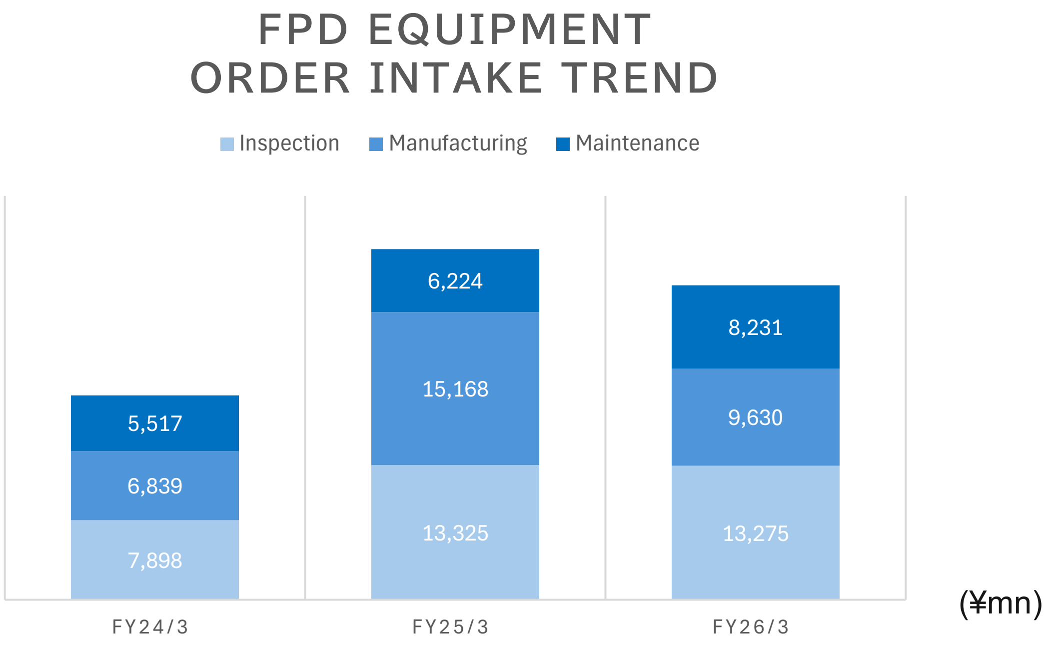
- ✓ Advanced packaging: Orders for DI exposure equipment for package substrates expanded
- ✓ Wafer inspection equipment orders also remained solid

FPD

- ✓ Maintenance increased, while CF exposure equipment and others were partially postponed
- ✓ Inspection equipment order intake remained relatively stable



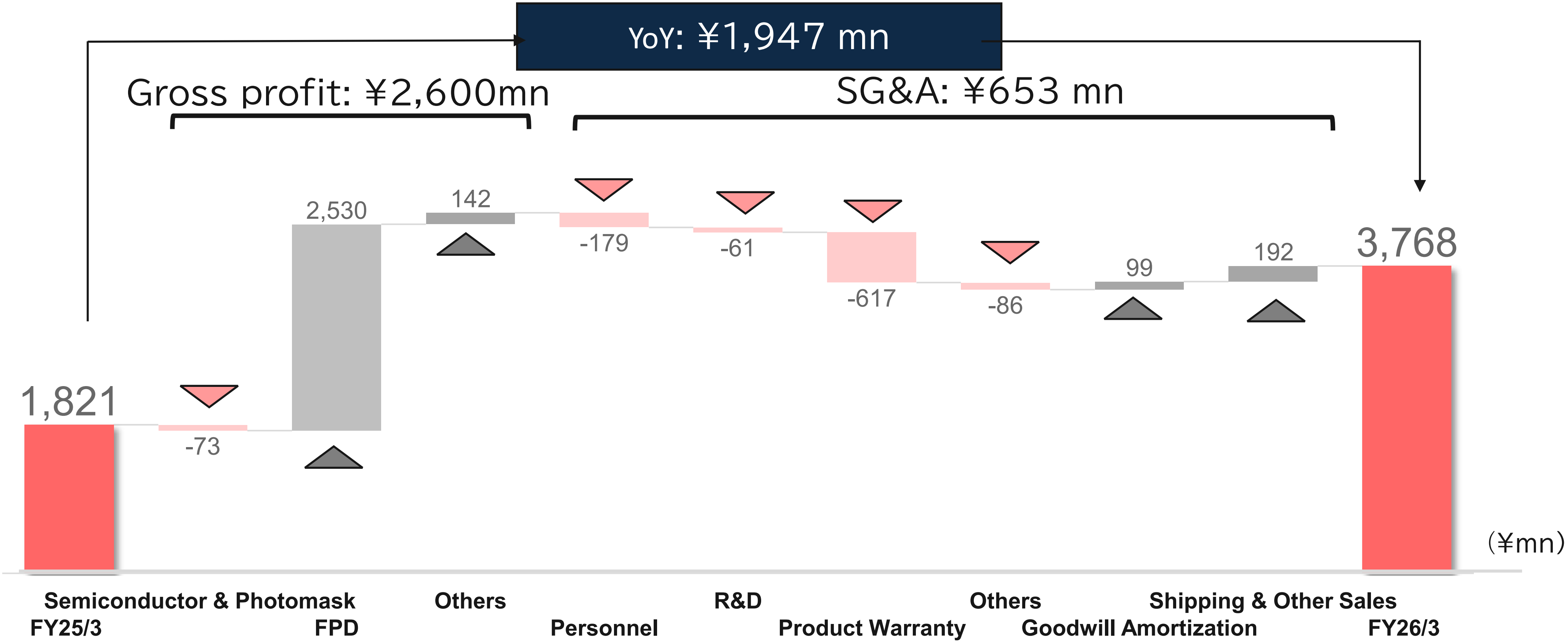
SEMICONDUCTOR & PHOTOMASK ORDER INTAKE TREND



FPD EQUIPMENT ORDER INTAKE TREND

Factors Affecting Operating Profit (YoY)

- ✓ Despite strong revenue growth in the Semiconductor & Photomask segment, gross profit did not increase due to a sharp decline in photomasks and the expansion of the low-margin trading-type business
- ✓ Product warranty-related costs increased in: (1) FPD equipment (amid localization in China), (2) photomasks, and (3) wafer inspection equipment



2027/3
Consolidated Earnings Forecast

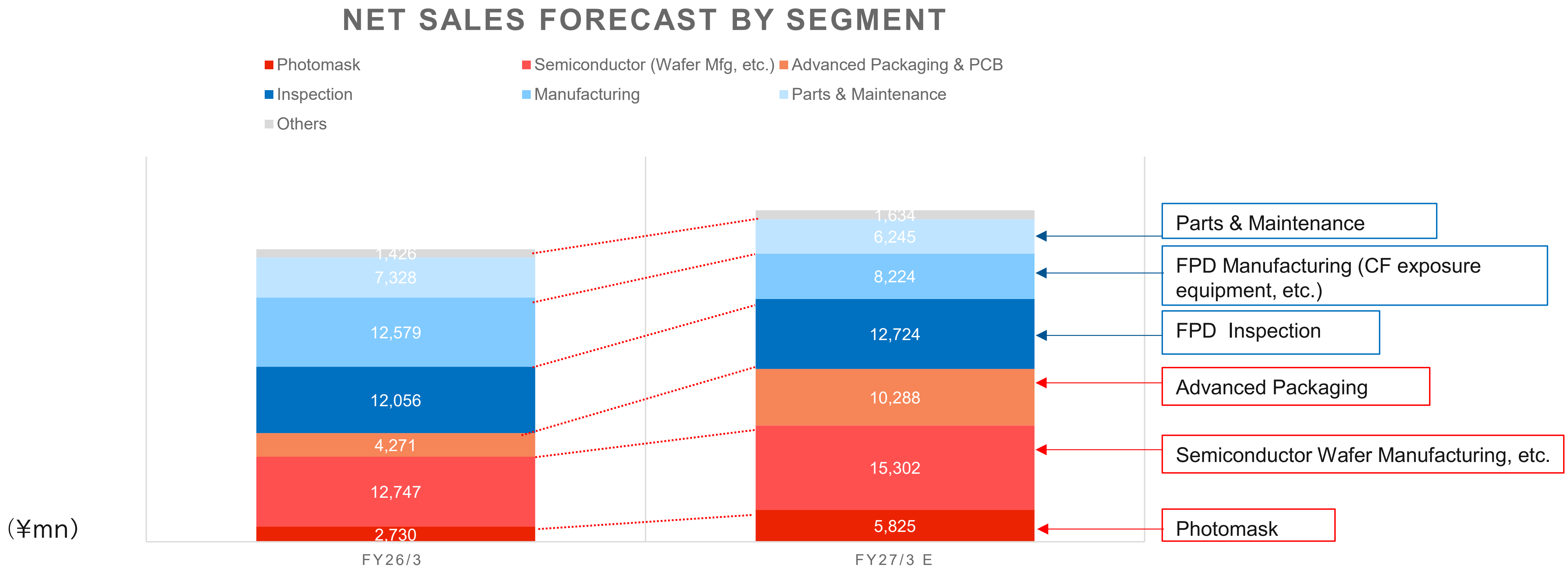
Earnings Forecast

- ✓ **Semiconductor & Photomask segment net sales expected to grow 60% YoY, a substantial expansion**
- ✓ **Semiconductor & Photomask segment profitability expected to exceed FPD**
- ✓ **Advanced packaging-driven orders expected to continue growing in FY27/3**

(¥mn)		FY2026/3	FY2027/3 Forecast	Change
Net Sales		**52,992**	**60,000**	+7,008
Operating profit		**3,768**	**5,500**	+1,732
Margin %		*7.1%*	*9.1%*	
Ordinary profit		**3,474**	**4,700**	+1,226
Margin %		*6.6%*	*7.8%*	
Net Profit attributable to owners of parent		**2,301**	**3,000**	+699
Margin %		*4.3%*	*5.0%*	
EPS (JPY)		243.48	317.35	+73.87
Dividend(JPY)	1st Half	40	40	-
	2nd Half	40	40	-
Payout ratio		32.9%	25.2%	

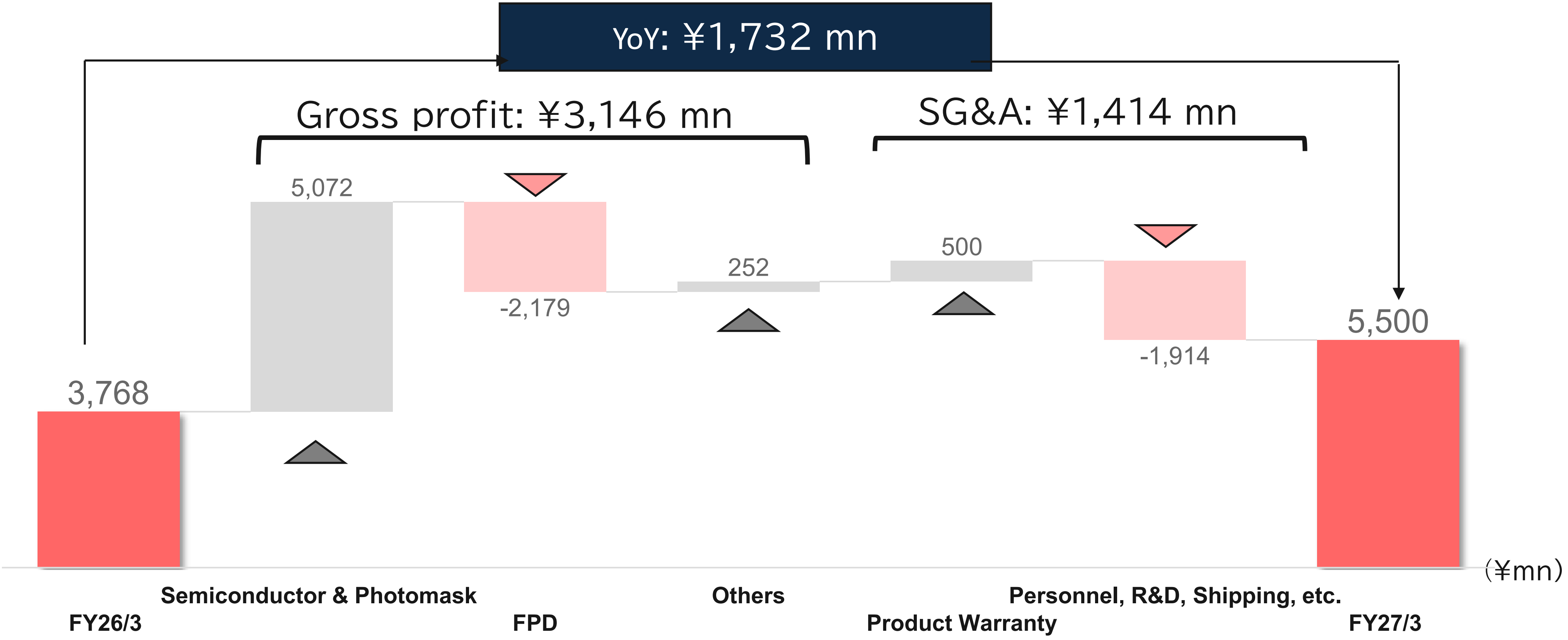
Net Sales Forecast by Segment

- ✓ **In the Semiconductor & Photomask segment, full-scale expansion of DI exposure equipment for advanced packaging expected to contribute**
- ✓ **Photomask expected to recover from the low level of FY26/3**
- ✓ **FPD equipment: While CF exposure equipment is expected to decline, inspection equipment is expected to remain strong**



Operating Profit Forecast

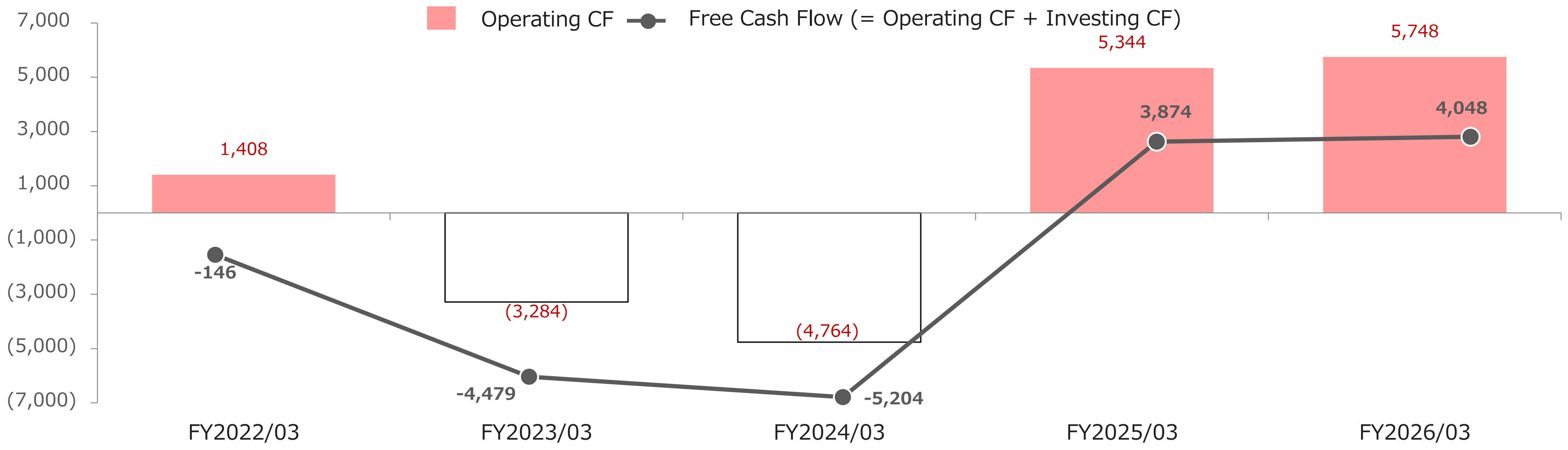
- ✓ Significant revenue growth expected in the Semiconductor & Photomask segment
- ✓ Product warranty-related costs expected to decrease; SG&A increases reflecting higher transportation costs amid recent geopolitical conditions



Capital Allocation

Improving Operating Cash Flow

- ✓ **FY26/3 operating cash flow improved; however, due to the rush of advanced packaging installations in FY27/3, it is expected to decrease**
- ✓ **Focus on improvement by shortening work-in-progress turnover months, including reducing equipment lead times**



(¥mn)

Dividends and Shareholder Returns

Aim for company-wide plan achievement and corresponding shareholder returns

- ✓ Consider stability, continuity, payout ratio, and necessary internal reserves through M&A for business expansion, capital expenditure, etc.
- ✓ Policy to return profits commensurate with business performance
- ✓ Annual dividend planned at ¥80, same as previous year. Aggressive returns also under consideration
- ✓ Will continue exploring flexible share buybacks to enhance returns

Items		FY22/3	FY23/3	FY24/3	FY25/3	FY26/3	FY27/3 (E)
Dividend amount (Total/¥mn)		1,176	882	586	765	765	765
Payout ratio (%)		*30.6*	*334.7*	*74.2*	*95.2*	*32.9*	*25.2*
Dividends per share (JPY)	1st Half	60	60	30	40	40	40
	2nd Half	60	30	30	40	40	40
	Total	120	90	60	80	80	80

ROE is the Top Priority Goal

FY26/3 missed-plan results taken seriously; full company commitment to achieving FY27/3 plan

	FY24/3	FY25/3	FY26/3	FY27/3E	FY29/3E
ROE	2.3%	2.4%	6.6%	8.0%	23.7%

Maximize Net Profit

Increase Net Sales

- ✓ Group-wide focus on growth areas
- ✓ (e.g., advanced packaging)
- ✓ M&A-driven creation of growth businesses

Improve Profit Margins

- ✓ Improve mix via Semiconductor & Photomask business expansion (high marginal profit)
- ✓ FPD-to-semiconductor group resource shift creating intra-group synergies

Shareholder Return Initiatives

Expand dividends with profit growth

- ✓ Stable dividends as baseline; raise dividends in growth phases based on plan-achievement confidence

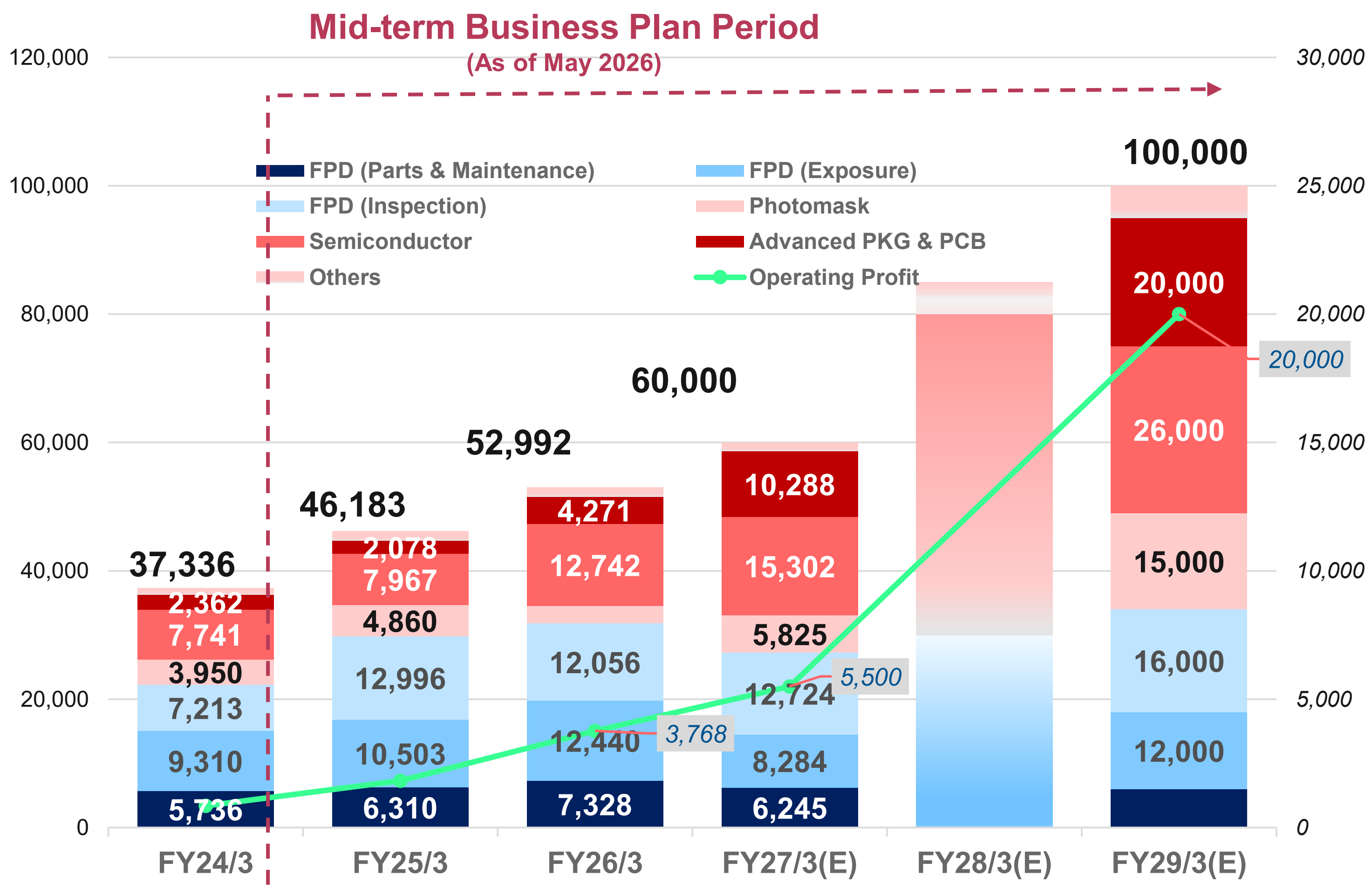
Flexible Share Buybacks

- ✓ While prioritizing dividends, execute flexible buybacks based on profitability and share price

Growth Strategy

Growth Strategy: Toward Achievement of the Mid-Term Business Plan

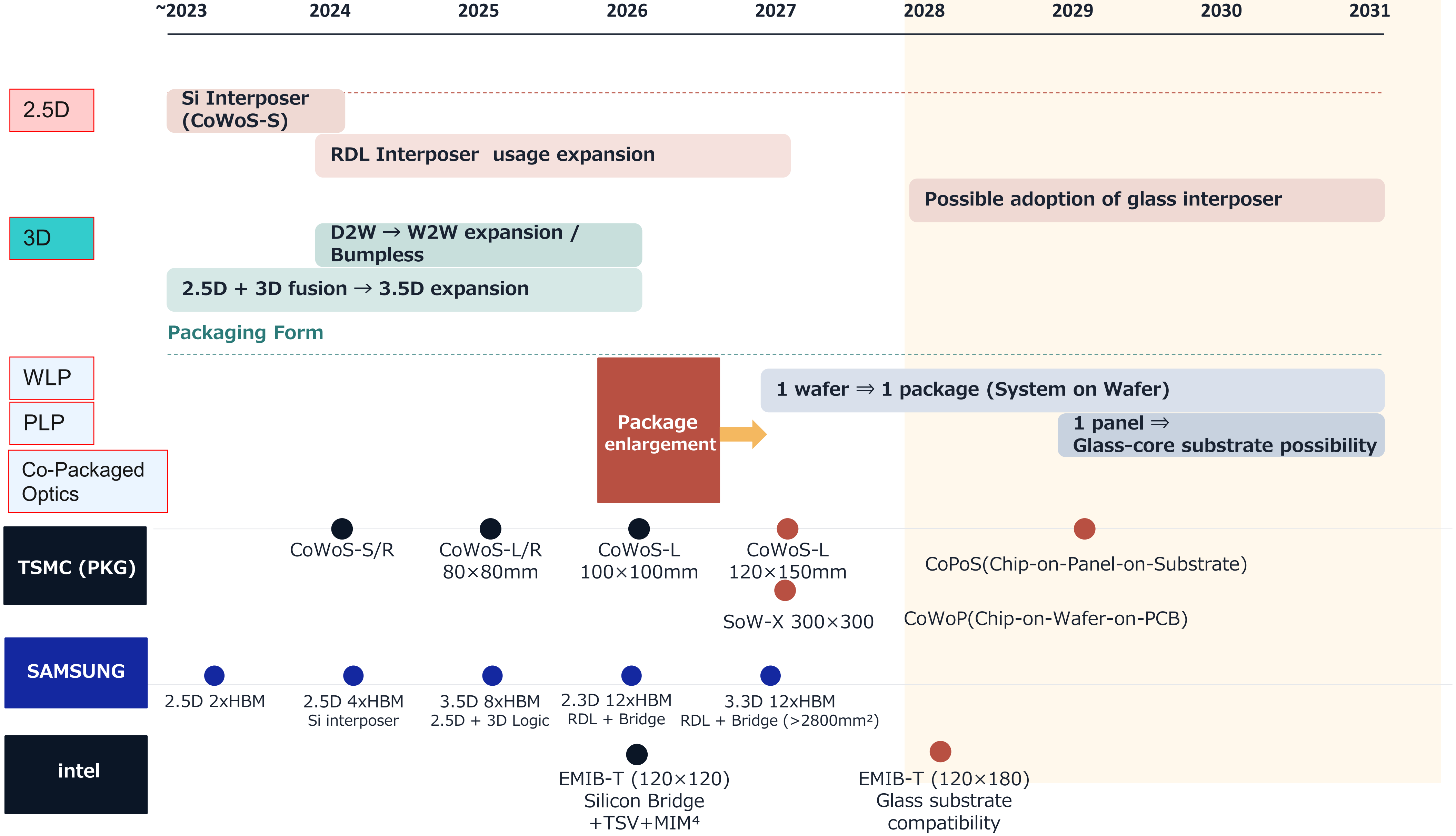
FY2029/3 company-wide target maintained (segment composition may change)
Continuing to drive order acquisition toward achievement



	Segment	Target Market	Flagship Products
Semi & Photomask	Advanced Packaging・PCB	- Semiconductor or package substrates - Standard PCB substrates	DI Exposure, O/S Tester
	Semiconductor	- Silicon wafers - Photoresist, etc.	- Inspection - Maskless exposure - Coater/Developer, etc.
	Photomask	- Legacy semiconductors - FPD	Inspection, defect repair, measurement, etc.
FPD	Inspection	LCD, OLED, etc.	Inspection, defect repair, measurement, etc.
	Exposure	LCD, etc.	Color filter exposure Photo-alignment exposure, etc.
	Parts & Maintenance	LCD, OLED, etc.	Service for delivered products

V-TECHNOLOGY

AI Semiconductor Advanced Packaging Technology Roadmap



~2023 | 2024 | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031

2.5D

Si Interposer (CoWoS-S)

RDL Interposer usage expansion

Possible adoption of glass interposer

3D

D2W → W2W expansion / Bumpless

2.5D + 3D fusion → 3.5D expansion

Packaging Form

WLP

PLP

Co-Packaged Optics

Package enlargement

1 wafer ⇒ 1 package (System on Wafer)

1 panel ⇒ Glass-core substrate possibility

TSMC (PKG)

CoWoS-S/R

CoWoS-L/R 80×80mm

CoWoS-L 100×100mm

CoWoS-L 120×150mm

SoW-X 300×300

CoPoS(Chip-on-Panel-on-Substrate)

CoWoP(Chip-on-Wafer-on-PCB)

SAMSUNG

2.5D 2xHBM

2.5D 4xHBM Si interposer

3.5D 8xHBM 2.5D + 3D Logic

2.3D 12xHBM RDL + Bridge

3.3D 12xHBM RDL + Bridge (>2800mm²)

intel

EMIB-T (120×120) Silicon Bridge +TSV+MIM⁴

EMIB-T (120×180) Glass substrate compatibility

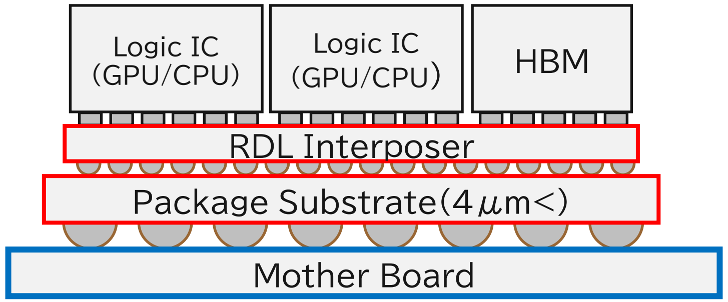
V-TECHNOLOGY

Strengthening the Advanced Packaging Business

AI semiconductor package focus; PC / smartphone-oriented packages via collaboration

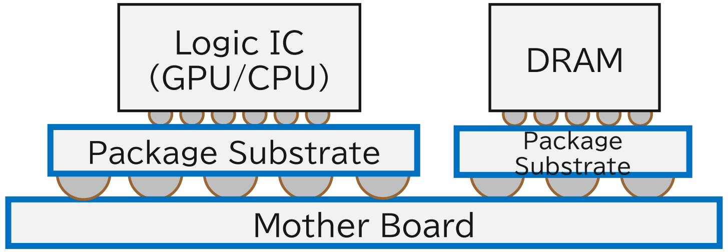
Semiconductor Package

AI semiconductor package(Advanced Package)
……**Chiplet(2.xD Package)**



Focus Areas (red frame)

PC, smartphone, etc. semiconductor packages
……**FC-BGA, FC-CSP**



Collaboration Areas (blue frame)

PCB

Deploying solutions to processes surrounding exposure

DI Exposure Equipment
Direct Imaging

★ China share ***No.1***

CFMEE 芯碁微装

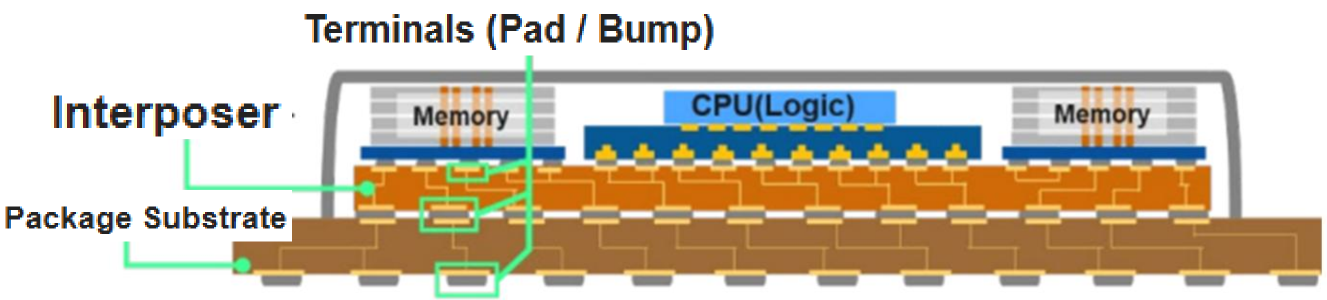
Deployment around the exposure process

- Wet equipment
- Printing equipment
- Inspection equipment and others

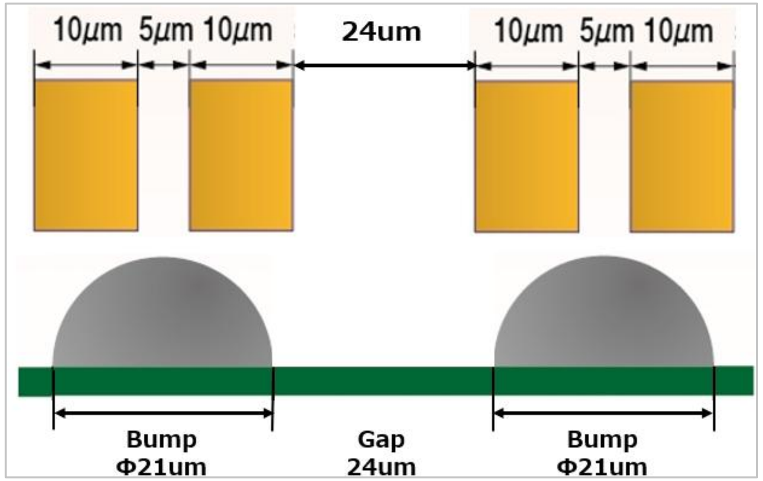
Advanced Packaging Tester

LIBRA tester

Microprobe



(Figure) Conceptual image of an advanced HPC package



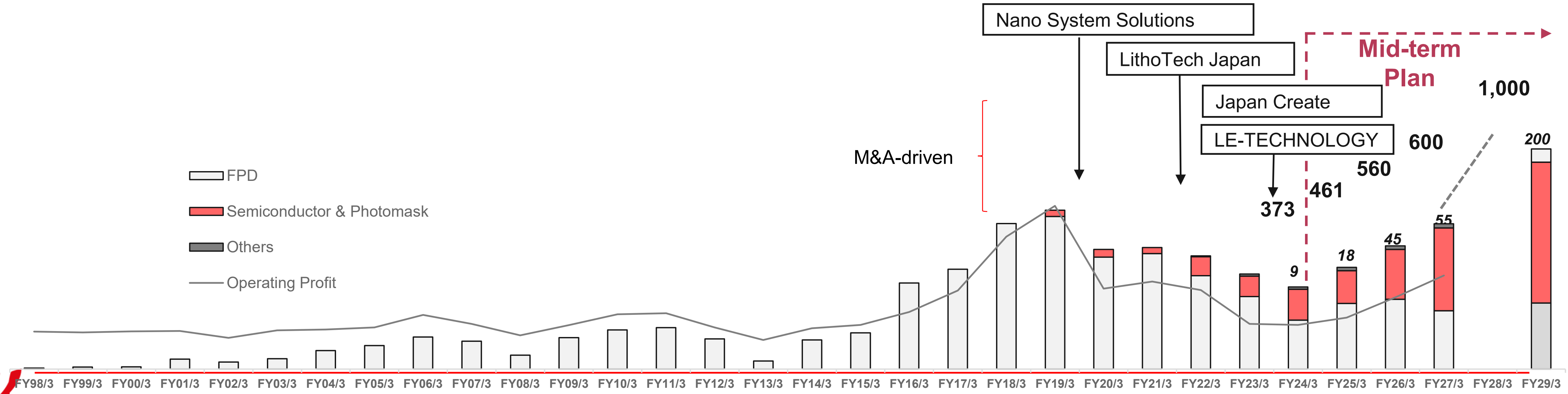
November 25, 2024 PR News Release

LIBRA is the world's first system enabling electrical inspection between terminals on package substrates and interposers (RDL) undergoing rapid pitch narrowing beyond the capabilities of conventional inspection. Dedicated to a wide variety of inspections, from intermediate wiring-layer stacking through final inspection, this system employs ultra-fine µ-probes developed by combining our group's proprietary technologies, achieving the industry-first four-terminal inspection at 25-µm pitch terminals. It is expected to find application in volume production lines.

Growth Strategy: FPD to Semiconductors, Shifting Growth Drivers

Entering semiconductor fields where Japan excels; joint development with customers is essential

Market Segments Entered	Leading Companies in the Industry	Our Group Companies	Main Products
Silicon wafers	Shin-Etsu Chemical, SUMCO, others	Nano System Solutions Japan Create	Silicon wafer inspection, cleaning
Photomasks	Tekscend Photomask, DNP, HOYA, others	V Technology	Inspection EQ (V-Tec original products)
Resist Materials	TOKYO OHKA KOGYO, JSR, Shin-Etsu Chemical, Sumitomo Chemical Co., FUJIFILM, others	LithoTech Japan	Resist Evaluation Equipment
Advanced Packaging	IBIDEN, Shinko Electric Industries, TOPPAN Holdings, others	LE-TECHNOLOGY OHT	DI Exposure Equipment, Open-Short Tester, Microprobe

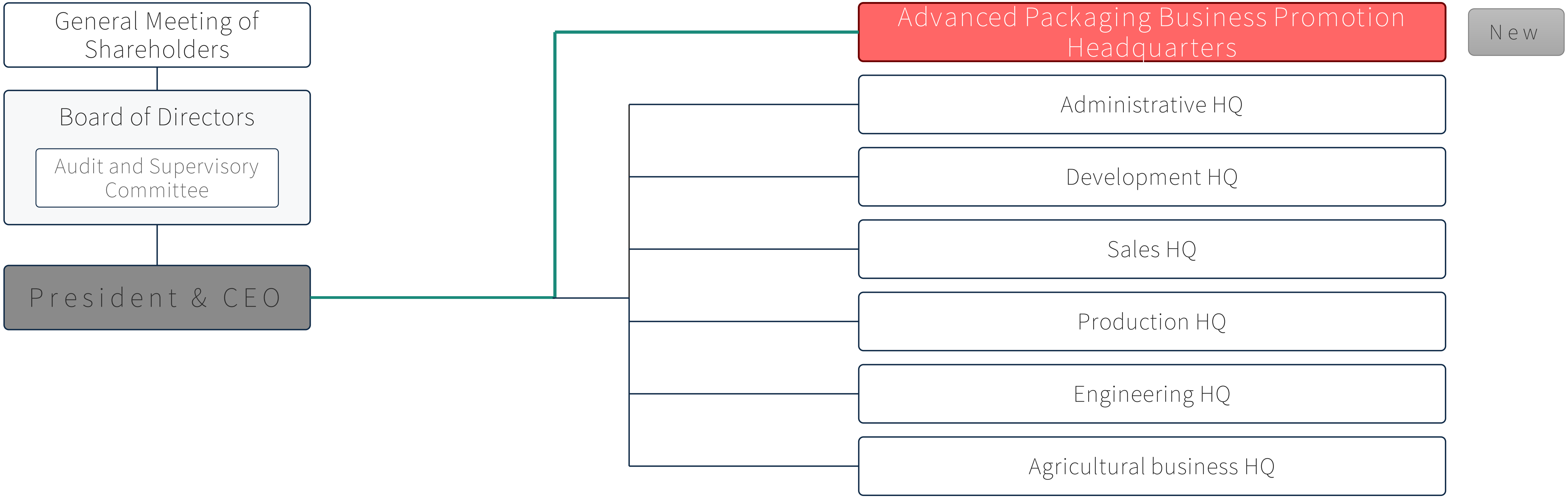


V-TECHNOLOGY

Advanced Packaging - New Organization

Establishing the Advanced Packaging Business Promotion Headquarters to strengthen execution

Organization Chart



General Meeting of Shareholders

Board of Directors

Audit and Supervisory Committee

President & CEO

Advanced Packaging Business Promotion Headquarters

New

Administrative HQ

Development HQ

Sales HQ

Production HQ

Engineering HQ

Agricultural business HQ

▶ The Advanced Packaging Business Promotion Headquarters, directly under the President & CEO, is responsible for unified group operations of the semiconductor packaging business.

DI Exposure Equipment LAMBDI Order Received from NEDO

For Advanced Packaging —
World-First Resolution Achieved

L/S = 0.5μm

DI Exposure Equipment
LAMBDI

DI Exposure Equipment LAMBDI Order Received from NEDO

World’s First L/S = 0.5μm-class Order for Advanced Packaging

V Technology Co., Ltd and its consolidated subsidiary, LE-TECHNOLOGY Co., Ltd, have successfully developed the world’s first L/S = 0.5μm-class DI (Direct Imaging) exposure system, LAMBDI, for interposers and package substrates, and have received an order from NEDO (New Energy and Industrial Technology Development Organization) through Osaka Metropolitan University.

The Group began shipping DI exposure systems capable of supporting 1μm-level wiring in August 2025, and has since achieved further improvements in resolution, leading to this order. Going forward, the Group will continue to develop innovative technologies that support the advancement of semiconductors and electronic devices, thereby contributing to the development of society.

April 7, 2026
News Release

1. Order Intake and Sales by Segment (¥mn)

	FY															
	FY24/3	FY25/3	FY26/3	FY27/3 E	FY24/3				FY25/3				FY26/3			
Item					1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
Order intake	**37,788**	**52,747**	**56,342**	**–**	**9,264**	**11,210**	**6,716**	**10,598**	**9,880**	**7,681**	**8,901**	**26,285**	**9,262**	**8,089**	**6,291**	**32,700**
Semiconductor & Photomask	16,444	16,562	23,381	–	2,592	5,872	2,283	5,763	2,255	4,120	6,037	4,151	3,547	3,800	2,962	13,072
Photomask	6,670	2645	2,681	–	250	2,790	484	3,146	590	700	1,351	4	0	2,040	90	551
SEM(Wafer/Labo/others)	7,549	9,393	12,947	–	2,281	1,988	1,299	1,982	960	2,564	3,151	2,719	2,598	1,746	2,533	6,070
Advanced Package･PCB	2,226	4,524	7,753	–	63	1,095	500	634	705	856	1,536	1,428	949	14	339	6,451
FPD	20,254	34,716	31,136	–	6,433	5,077	4,174	4,569	7,237	3,248	2,511	21,721	5,346	3,957	2,959	18,874
Inspection	7,898	13,325	13,275	–	1,037	3,604	2,285	973	2,944	1,731	1,137	7,513	1,839	757	1,104	9,575
Manufacturing	6,839	15,168	9,630	–	4,339	-1	554	1,948	2,905	0	258	12,005	2,287	1,328	12	6,003
Maintenance	5,517	6,224	8,231	–	1,058	1,475	1,336	1,649	1,388	1,516	1,116	2,204	1,220	1,872	1,843	3,296
Others	1,090	1469	1,824	–	239	261	258	266	388	314	354	413	368	332	370	754
Margin of SPE	43.5%	31.4%	41.5%	–	28.0%	52.4%	34.0%	54.4%	22.8%	53.6%	67.8%	15.8%	38.3%	47.0%	47.1%	40.0%
Order Backlog	**37,100**	**43,664**	**47,013**	**–**	**40,162**	**44,787**	**44,734**	**37,100**	**37,456**	**32,316**	**31,737**	**43,664**	**44,927**	**41,271**	**35,248**	**47,013**
Semiconductor & Photomask	17,200	18,857	22,629	–	15,958	19,809	18,162	17,200	17,959	18,168	21,151	18,857	18,087	17,055	15,716	22,629
FPD	19,899	24,877	23,986	–	24,204	24,978	26,571	19,899	19,497	14,147	10,586	24,877	26,840	24,216	19,532	23,986
Others	0	0	398	–	0	0	0	0	0	0	0	0	0	0	0	398
Margin of SPE	45.5%	43.2%	48.1%	–	39.7%	44.2%	40.6%	45.5%	47.9%	56.2%	66.6%	43.2%	40.3%	41.3%	44.6%	48.1%
Net sales	**37,336**	**46,183**	**52,993**	**60,000**	**5,749**	**6,585**	**6,769**	**18,231**	**9,523**	**12,822**	**9,479**	**14,358**	**7,999**	**11,744**	**12,315**	**20,935**
Semiconductor & Photomask	14,053	14,905	19,593	31,415	1,377	2,020	3,931	6,724	1,495	3,911	3,055	6,444	4,317	4,832	4,285	6,159
Photomask	3,950	4,860	2,730	5,825	67	270	862	2,751	734	1,687	985	1,455	1,536	119	700	375
SEM(Wafer/Labo/others)	7,741	7,967	12,592	15,302	831	1,377	2,122	3,412	642	2,116	1,542	3,667	1,327	3,758	2,449	5,058
Advanced Package･PCB	2,362	2,078	4,271	10,288	480	374	947	627	120	108	527	1,323	1,454	955	1,136	726
FPD	22,259	29,809	31,963	27,253	4,133	4,303	2,581	11,242	7,639	8,598	6,071	7,501	3,314	6,580	7,648	14,421
Inspection	7,213	12,996	12,056	12,724	197	308	832	5,876	3,648	3,859	2,895	2,594	2,182	3,772	2,417	3,685
Manufacturing	9,310	10,503	12,579	8,284	2,620	2,599	314	3,777	2,591	3,065	1,654	3,193	266	767	3,308	8,238
Maintenance	5,736	6,310	7,328	6,245	1,316	1,397	1,435	1,588	1,400	1,674	1,522	1,714	866	2,041	1,924	2,497
Others	1,024	1,469	1,436	1,332	239	261	258	266	388	314	354	413	368	332	380	356
Margin of SPE	37.6%	32.3%	37.0%	52.4%	24.0%	30.7%	58.1%	36.9%	15.7%	30.5%	32.2%	44.9%	54.0%	41.1%	34.8%	29.4%

(Including Maintenance)

V-TECHNOLOGY

2. Order Intake, Performance Results, and Guidance(¥mn)

Item	2020/3	2021/3	2022/3	2023/3	2024/3	2025/3	2026/3	2027/3E	2025/3				2026/3			
									1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
Order intake	22,532	36,980	53,200	37,072	37,788	52,747	56,342	-	9,879	7,682	8,901	26,285	9,262	8,089	6,291	32,700
Order backlog	59,145	40,939	42,721	36,647	37,100	43,664	47,013	-	37,456	32,316	31,737	43,664	44,928	41,271	35,248	47,013
Net sales	54,322	55,186	51,418	43,146	37,335	46,182	52,992	60,000	9,523	12,822	9,479	14,358	7,998	11,746	12,313	20,935
Gross profit	15,122	15,704	15,486	10,946	10,604	12,130	14,730	-	1,773	3,375	2,547	4,435	1,854	2,658	3,878	6,340
Operating profit	5,653	6,604	5,461	986	846	1,821	3,768	5,500	-948	812	192	1,765	-514	144	997	3,141
Non-operating income	623	395	518	935	551	517	731	-	287	-154	353	31	139	59	248	285
Non-operating expenses	121	163	111	222	285	447	1025	-	97	175	76	99	215	19	84	707
Ordinary Profit	6,156	6,836	5,868	1,700	1,112	1,891	3,474	4,700	-759	484	469	1,697	-589	183	1,161	2,719
Pre-tax profit	6,191	7,054	6,450	1,571	1,181	1,383	3,425	-	-721	504	451	1,149	-633	269	1,417	2,372
Corporate taxes	2,054	2,462	2,194	1,434	603	781	1058	-	-6	101	213	473	60	-194	-131	1,323
Net Profit attributable to owners of parent	3,251	3,513	4,198	260	778	800	2,301	3,000	-656	440	269	747	-665	426	1,543	997
Net profit per share*	336.29	363.41	434.21	26.92	80.65	84.07	243.48	317.35	-68.22	45.41	5.63	78.44	-70.46	45.13	163.37	105
Dividends per share	120	120	120	90	60	80	80	80	-	40	-	40	-	40	-	40
Net assets per share	2926.03	3233.74	3534.4	3475.25	3571.35	3544.98	3825.9	-	-	-	-	3544.98	-	-	-	3825.9
Gross profit margin	27.8%	28.5%	30.1%	25.4%	28.4%	26.3%	27.8%	-	18.6%	26.3%	26.9%	30.9%	23.2%	22.6%	31.5%	30.3%
Operating profit margin	10.4%	12.0%	10.6%	2.3%	2.3%	3.9%	7.1%	9.2%	-10.0%	6.3%	2.0%	12.3%	-6.4%	1.2%	8.1%	15.0%
Ordinary profit margin	11.3%	12.4%	11.4%	3.9%	3.0%	4.1%	6.6%	7.8%	-8.0%	3.8%	4.9%	11.8%	-7.4%	1.6%	9.4%	13.0%
Corporate tax rate	33.2%	34.9%	34.0%	91.3%	51.1%	56.5%	30.9%	-	0.83%	20.04%	47.23%	41.17%	-9.5%	-72.1%	-9.2%	55.8%
Net profit margin	6.0%	6.4%	8.2%	0.6%	2.1%	1.7%	4.3%	5.0%	-6.9%	3.4%	0.6%	5.2%	-8.3%	3.6%	12.5%	4.8%
ROE	11.5%	11.2%	12.7%	0.8%	2.3%	2.4%	6.6%	8.0%	-2.0%	1.3%	0.2%	2.2%	-2.0%	1.3%	3.8%	2.8%
Shareholders' Equity	28,293	31,268	32,980	32,842	34,372	33,500	36,167	-	33,611	32,976	33,153	33,500	32,634	33,172	34,699	36,167

*Weighted average shares outstanding, excluding treasury shares

3. Balance Sheet and Cash Flow Statement (¥mn)

Item	2021/3	2022/3	2023/3	2024/3	2025/3	2026/3	2025/3				2026/3			
							1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
Assets														
Cash & Deposits	33,278	27,898	26,729	23,096	26,671	29,475	25,063	28,930	26,196	26,671	23,129	19,952	23,569	29,475
Notes Receivable and Accounts Receivable	19,329	19,537	22,408	24,716	19,786	17,494	20,332	21,681	20,181	19,786	18,085	21,598	19,352	17,494
Inventories	15,956	11,405	10,089	15,531	15,495	14,200	16,408	15,052	17,057	15,495	18,196	18,131	20,600	14,200
Merchandise and Supplies	196	176	338	477	679	633	443	787	788	679	941	625	1,205	633
Work in Progress	13,977	9,428	7,219	12,274	10,707	10,160	12,881	11,374	12,951	10,707	12,612	13,545	15,750	10,160
Raw Materials and Supplies	1,783	1,801	2,532	2,780	4,109	3,407	3,084	2,891	3,318	4,109	4,643	3,961	3,645	3,407
Current Assets	71,379	63,085	62,621	67,045	65,392	64,464	65,537	69,073	67,255	65,392	62,922	63,018	67,440	64,464
Property, Plant and Equipment	4,382	4,720	4,034	4,098	3,859	4,103	4,305	4,261	4,221	3,859	4,403	4,443	4,325	4,103
Intangible Assets	1,625	1,495	1,460	886	712	709	1,000	957	879	712	648	586	537	709
Investments and Other Assets	3,203	3,300	3,270	3,575	3,235	3,771	3,553	3,190	3,105	3,235	3,157	3,619	4,419	3,771
Total Assets	80,591	72,601	71,387	75,606	73,201	73,049	74,397	77,483	75,461	73,201	71,132	71,668	76,721	73,049
Liabilities														
Notes and Accounts Payable	6,477	6,323	4,039	5,429	4,918	4,306	5,296	4,778	4,932	4,918	5,735	5,031	6,018	4,306
Short-term Borrowings	120	394	663	866	1,295	2,161	1,386	1,704	1,685	1,295	1,297	1,868	1,784	2,161
Advances Received	15,061	8,334	8,221	4,496	5,037	4,254	5,645	5,638	5,113	5,037	5,563	5,892	5,752	4,254
Current Liabilities	34,195	27,061	23,922	29,299	24,263	22,773	29,905	26,474	25,650	24,263	24,404	25,078	27,054	22,773
Long-Term Borrowings	12,964	10,243	12,662	10,550	14,254	12,718	9,482	16,745	15,420	14,254	12,819	12,167	13,698	12,718
Net Assets	32,195	34,540	33,884	34,639	33,581	36,250	33,841	33,154	33,300	33,581	32,691	33,258	34,771	36,250
Shareholders’ Equity	31,268	34,175	33,604	34,372	33,500	36,167	33,611	32,976	33,153	33,500	32,634	33,172	34,699	36,167
Consolidated CF														
CF from Operating Activities	20,173	1,408	-3,284	-4,764	5,344	5,748	–	–	–	–	–	–	–	–
CF from Investing Activities	-1,251	-1,554	-1,195	-440	-1,470	-1,700	–	–	–	–	–	–	–	–
Free Cash Flow	18,922	-146	-4,479	-5,204	3,874	4,048	–	–	–	–	–	–	–	–
Purchase of Treasury Stock	-512	0	0	-99	-499	0	–	–	–	–	–	–	–	–
Dividends Paid	-974	-1,176	-1,176	-588	-675	-765	–	–	–	–	–	–	–	–
CF from Financing Activities	1,972	-5,839	2,780	1,526	-471	-1565	–	–	–	–	–	-	–	–

V-TECHNOLOGY

Business Segments

Operating Segment	Sub-segment	Related Markets	Key Products	V Technology Group
Semiconductor & Photomask	Photomask	・Photomasks for legacy semiconductors ・FPD photomasks	Inspection related, etc.	V Technology
	Semiconductor	・Silicon wafers ・Photoresist ・Semiconductor prototyping, etc.	・Inspection ・Laboratory development ・Maskless exposure, etc.	• Nano System Solutions • LithoTech Japan • Japan Create
	Advanced Packaging・PCB	・Advanced Packaging ・Standard PCB substrates	・DI Exposure ・O/S Tester	• LE-TECHNOLOGY • OHT • V Technology
FPD	Inspection	LCD, OLED, other uses	Inspection related, etc.	• V Technology • OHT
	Exposure	LCD, other uses	Color filter exposure, Photo-alignment exposure, etc.	V Technology
	Parts & Maintenance	LCD, OLED, other uses	Product services, etc.	V Technology, and others

Note

- **Future Outlook**

  This document's descriptions of our plans, strategies, forecasts and other non-historical facts are forward-looking statements based on currently available expectations, estimates and forecasts. These expectations, estimates and forecasts are subject to a number of potential risks, uncertainties and processes, including changes in economic and market conditions, changes in the competitive environment, changes in the policies of countries where our customers are located, and the outcome of pending and future litigation, which could cause actual results to differ materially from those projected. Accordingly, you are advised not to place undue reliance on these forward-looking statements. The company undertakes no obligation to update these forward-looking statements based on new information, future events or otherwise.

- **Treatment of Figures**

  Amounts shown are rounded down to the nearest unit and percentages are rounded to the nearest unit amount; these may not correspond to the breakdown.

- **Business Segment Composition**
  - ✓ **Semiconductor and Photomask Equipment Business**

    This segment is made up of the development, design, manufacture, sales and related services of manufacturing equipment, inspection equipment and photomask equipment for the semiconductor manufacturing process, as well as PCB equipment.

  - ✓ **FPD Business (FPD)**

    This segment is made up of the development, design, manufacture, sales and related services of manufacturing equipment, inspection equipment and other equipment for the FPD manufacturing process, as well as materials such as evaporation masks for OLEDs.

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